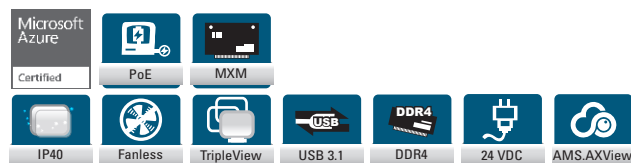


eBOX671-521-FL

Fanless Embedded System with LGA1151 9th/8th Gen Intel® Core™ i7/i5/i3 & Celeron® Processor, 4-CH PoE and MXM 3.1 Type A

Features

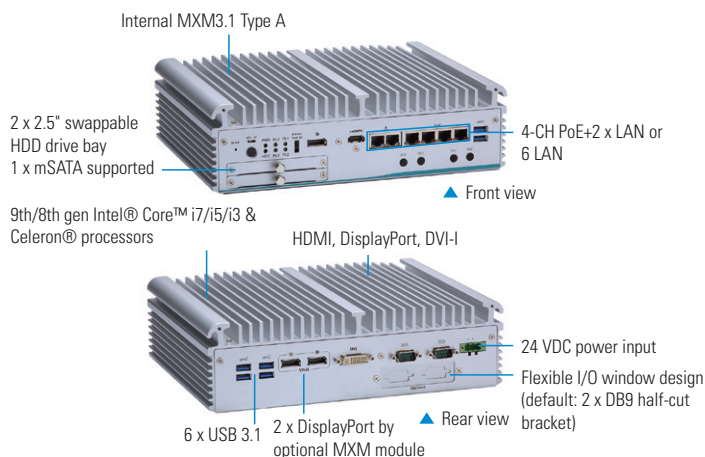
- 9th/8th gen Intel® Core™ i7/i5/i3 & Celeron® with Intel® Q370 chipset (Coffee Lake/Coffee Lake Refresh-S)
- 4-CH PoE (IEEE802.3at compliance)
- Dual swappable 2.5" SATA HDD drive bays with RAID 0 & 1
- Supports MXM 3.1 type A graphics module (optional)
- DVI-I, HDMI, and DisplayPort with triple-view supported
- AMS.AXView intelligent remote monitoring software for IIoT



Specifications

Standard Color	Silver
Construction	Aluminum extrusion and heavy-duty steel, IP40
CPU	LGA1151 9th gen Intel® Core™ i7/i5/i3 & Celeron® processors (35W) LGA1151 8th gen Intel® Core™ i7/i5/i3 & Celeron® processors (35W/65W)
System Memory	2 x 260-pin DDR4-2666 SO-DIMM, up to 64GB (ECC supported by Intel® C246 PCH)
Chipset	Intel® Q370/optional Intel® C246 PCH
BIOS	AMI
System I/O Outlet	2 x RS-232/422/485 2 x DisplayPort via optional MXM kit 1 x HDMI, 1 x DisplayPort, 1 x DVI-I 4 x Power over Ethernet (IEEE802.2at), up to 60W 2 x 10/100/1000 Mbps Ethernet (Intel® i210-IT & i219-LM) 4 x USB 3.1 Gen2, 2 x USB 3.1 Gen1 1 x Phoenix type VDC power input connector 1 x AT/ATX quick switch 1 x ATX power switch 1 x Reset switch 1 x Remote switch 1 x Flexible I/O window (Default : 2 x DB9 half-cut bracket) 4 x SMA-type antenna connector
Watchdog Timer	255 levels, 1 to 255 sec.
Storage	2 x 2.5" HDD drive bay (max. up 9.5 mm height) 1 x mSATA (enabled in BIOS setting)
Expansion Interface	2 x Full-size PCI Express Mini Card slot (USB + PCIe signal) 2 x SIM slot 1 x MXM3.1 type A connector
TPM	TPM 2.0
System Indicator	1 x Green LED for system power-on 1 x Green LED for HDD active 4 x Green LED for programmable
Power Input	24 VDC
Operating Temperature	Without MXM module: -40°C to 60°C (-40°F to +140°F) (with W.T. DRAM & SSD, CPU TDP 35W) -40°C to 50°C (-40°F to +122°F) (with W.T. DRAM & SSD, CPU TDP 65W) With MXM module: -40°C to 50°C (-40°F to +122°F) (with W.T. DRAM & SSD & MXM kit, CPU TDP 35W)
Humidity	10% - 90%, non-condensing
Shock Vibration	IEC 60068-2-27 (w/ SSD: 50G, half-sine, 11 ms duration)
Vibration Endurance	IEC 60068-2-64 (w/ SSD: 3Grms STD, random, 5 - 500 Hz, 1 hr/axis)
Dimensions	280 mm (11.02") (W) x 210 mm (8.26") (D) x 80.5 mm (3.16") (H)
Weight (net/gross)	4.8 kg (10.58 lb)/5.6 kg (12.34 lb)
Certifications	CE, FCC Class A
EOS Support	Win 10 IoT, Linux
Software Support	AMS.AXView

* W.T.: Wide Temperature. All W.T. supported products have to be sorted by Axiomtek.



Packing List

- 1 x Screw pack
- 4 x Pre-installed foot pad
- 1 x 3-pin terminal block connector
- 1 x Remote switch cable

Power Protection

DC Version

- OVP (over voltage protection)
- UVP (under voltage protection)
- OCV (over current protection)
- SCP (short circuit protection)
- Reserve protection

Ordering Information

Standard

eBOX671-521-FL-DC-4PoE (P/N: E36K671105)	Fanless embedded system with LGA1151 9th/8th gen Intel® Core™ i7/i5/i3 & Celeron® processor, Intel® Q370, DVI-I, HDMI, dual HDD, 4 PoE, 2 GbE LAN, 6 USB, 2 COM and 24 VDC
eBOX671-521-FL-DC-6GbE (P/N: E36K671106)	Fanless embedded system with LGA1151 9th/8th gen Intel® Core™ i7/i5/i3 & Celeron® processor, Intel® Q370, DVI-I, HDMI, dual HDD, 6 GbE LAN, 6 USB, 2 COM and 24 VDC

Optional

2.5" SATA HDD	80GB or above
2.5" SATA SSD	100GB or above
DDR4 SO-DIMM	4GB to 32GB
mSATA	64GB or above
8816K6718A0E	Wall mount kit
8816K671CA0E	DIN-rail kit
	3G/LTE module
8816K671BA0E	MXM1050 kit
8816K671AA0E	MXM1030 kit
50906D24000E	24V 120W power adapter
	Power cord
E392903102	AX92903 CANbus PCI Express Mini module
E392902103	AX92902 LAN PCI Express Mini module
59406392140E	RS-232 cable, L=200 mm for COM3/4
E392904102	AX92904 DIO PCI Express Mini module
E392905103	AX92905 Audio PCI Express Mini module
E392918103	AX92918 Dual LAN PCI Express Mini module

* Specifications and certifications may vary based on different requirements.

Dimensions

